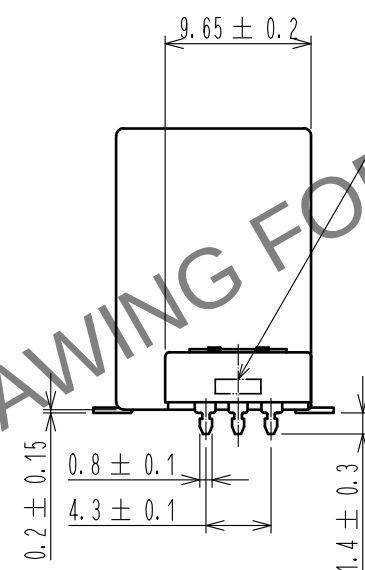
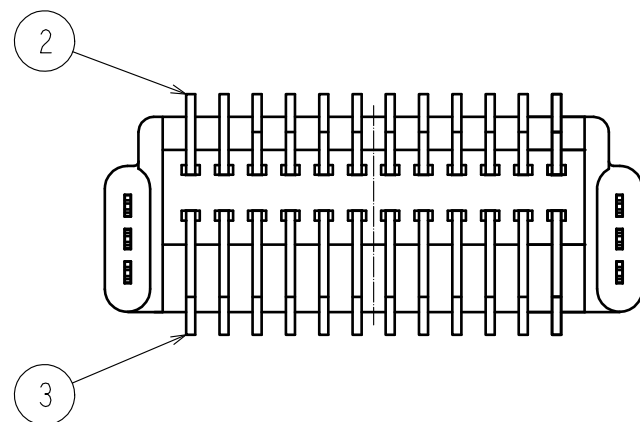
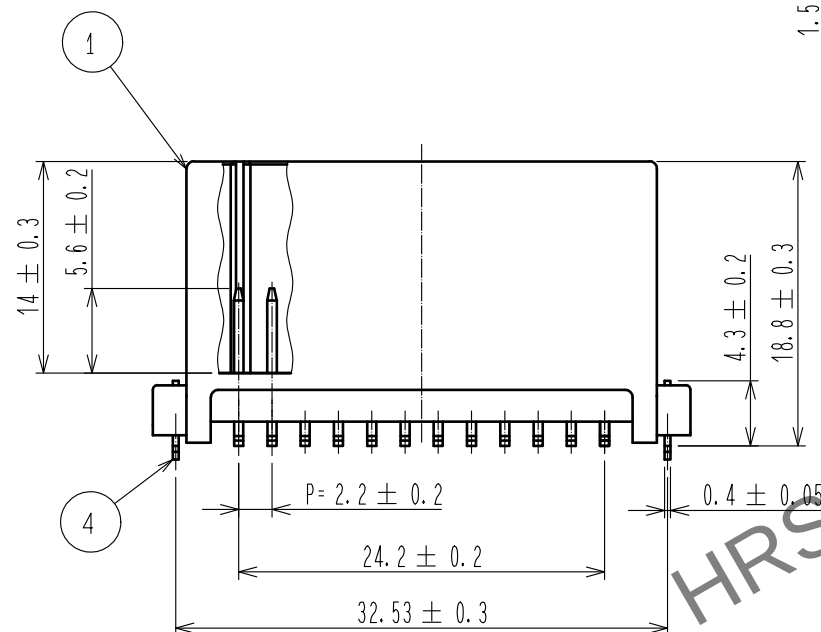
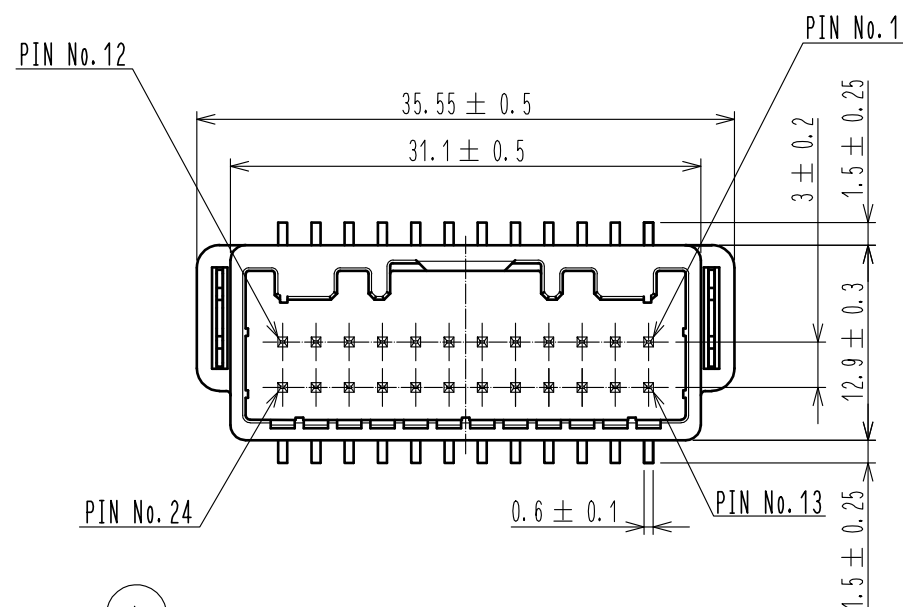


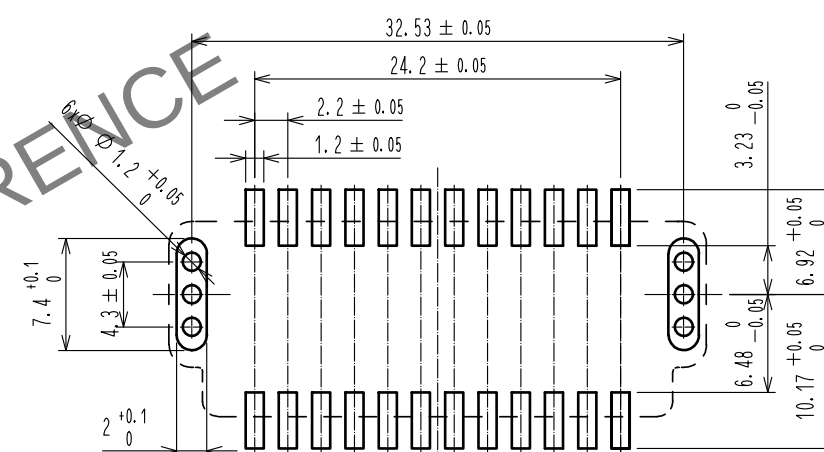
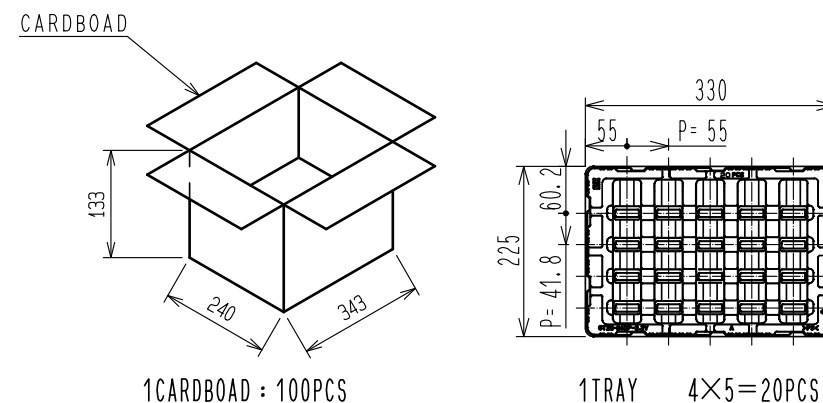
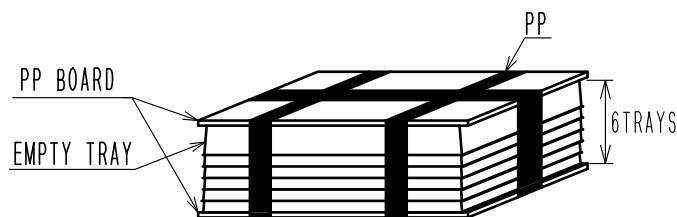
△ 端子No. 追記



LOT NO

TRAY PACKING SPECIFICATIONS

6 TRAYS STACKING.
ODD NUMBER TRAYS AND EVEN NUMBER TRAYS ARE REVERSE DIRECTION.
TOP TRAY IS EMPTY.



RECOMMENDED PC BOARD PATTERN

NOTE1. RECOMMENDED TEMPERATURE PROFILE FOR REFLOW
(REFER TO RIGHT FIG.)

USED REFLOW SYSTEM

: IR IN THE AIR OR NITROGEN

NO. OF CYCLES : 2 MAX

PEAK : 250°C

OVER 230℃ : 20~40s

PREHEAT : 150~180℃

60~120s

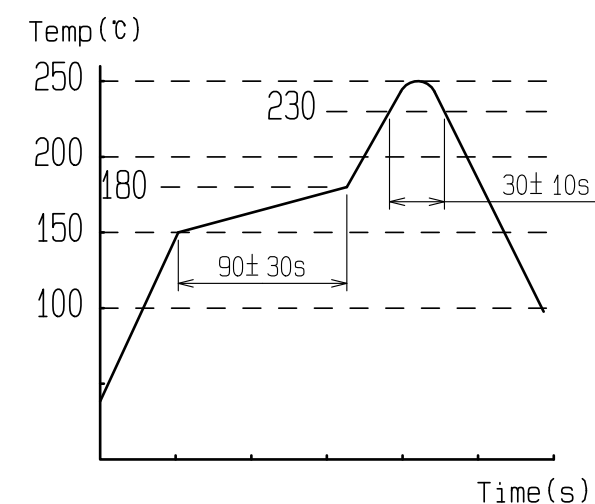
2. TEMPERATURE FOR SOLDERING IRON

:280~300°C WITHIN 2s

3. CO-PLANARITY SHALL BE 0.1 MAX.

4. PC BOARD THICKNESS=1.6.

5. RECOMMENDED SOLDER THICKNESS=0.15



2	BRASS	TIN PLATING	T=0.64	4	BRASS	TIN PLATING	T=0.4
1	PPS	LIGHT GRAY		3	BRASS	TIN PLATING	T=0.64
NO.	MATERIAL	FINISH , REMARKS		NO.	MATERIAL	FINISH , REMARKS	

UNITS mm		SCALE 2 : 1	COUNT 	DESCRIPTION OF REVISIONS DIS-T-00008740	DESIGNED AN. SAIKI	CHECKED HH. TSUKUMO	DATE 20210321
 HIROSE ELECTRIC CO., LTD.		APPROVED : HK. UMEHARA	20201001	DRAWING NO. EDC-166657-86-00			
		CHECKED : HK. UMEHARA	20201001	PART NO. GT25-24DP-2. 2V(56)			
		DESIGNED : DONGCHAN KIM	20201001	CODE NO. CL0775-0021-0-86			
		DRAWN : DONGCHAN KIM	20201001	 			